PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company	577	STMicroelectronics International N.V
1.2 PCN No.		MDG/21/12540
1.3 Title of PCN		Amkor ATP (Philippines) TSSOP20 package additional line for STM32G listed products
1.4 Product Category		STM32G03 64K in TSSOP20 package
1.5 Issue date		2021-04-26

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	NEMETH KRISZTINA	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change			
3.1 Category	3.2 Type of change	3.3 Manufacturing Location	
Transfer	Line transfer for a full process or process br (process step, control plan, recipes) from on site to another site: Assembly site (SOP 261	e	

4. Description of change		
Old New		New
4.1 Description	Back-End Source: - ST Shenzhen (China)	Back-End Source: - ST Shenzhen (China) - AMKOR ATP (Philippines) Added
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Lead color and surface finish will change due to different leadframe finishing. Pin1 identifier might change in terms of form and positioning. Package darkness changes depending on molding.	

5. Reason / motivation for change		
5.1 Motivation To sustain MCD microcontrollers success in the market, ST Microcontrollers Division microconvert the line to maintain state of the art service level to our customers		
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change		
	Second level interconnect changes from e4 to e3. Tracability ensured by ST internal Tools.	

7. Timing / schedule	
7.1 Date of qualification results	2021-04-08
7.2 Intended start of delivery	2021-05-14
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
3.1 Description 12540 MDG-MCD-RER1712 V3.0 - PCN10233-PCN12540-ATP1 TSSOP20 XDLF for additional source - reliability evaluation report.pdf			
8.2 Qualification report and qualification results		Issue Date	2021-04-26

9. Attachments (additional documentations)

12540 Public product.pdf 12540 MDG-MCD-RER1712 V3.0 - PCN10233-PCN12540-ATP1 TSSOP20 XDLF for additional source - reliability evaluation report.pdf 12540 PCN12540_Additional information.pdf

10. Affected parts			
10. 1 Current		10.2 New (if applicable)	
10.1.1 Customer Part No 10.1.2 Supplier Part No		10.1.2 Supplier Part No	
	STM32G031F8P6		

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